



Robert Greene Steme Edward J. Kessler Jorge A. Goldstein David K.S. Cornwell Robert W. Esmond Tracy-Gene G. Durkin Michael B. Ray Robert E. Sokohl Eric K. Steffe Michael Q. Lee Steven R. Ludwig John M. Covert Linda E. Alcorn Robert C. Millonig Donald J. Featherstone Timothy J. Shea, Jr Lawrence B. Bugaisky Michael V. Messinger Judith U. Kim Patrick E. Garrett Jeffrey I. Helvey Heidi L. Kraus Eldora L. Ellison Thomas C. Fiala Albert L. Ferro\* Donald R. Banowit Peter A. Jackman Teresa U. Medler Jeffrey S. Weaver Kendrick P. Patterson Vincent L. Capsuano Brian J. Del Buono Virgil Lee Beaston Preedore A. Wood Elizabeth J. Haanes Joseph S. Ostroff Frank R. Cottingham Christine M. Lhulier Rae Lynn P. Guest

April 20, 2005

George S. Bardmesser Daniel A. Klein Jason D. Eisenberg Michael D. Specht Andrea J. Kamage Tracy L. Muller Jon E. Wright LuAnne M. DeSantis Ann E. Summerfield Aric W. Ledford Helene C. Carlson Cynthia M. Boucher Timothy A. Doyle\* Gaby L. Longsworth Lori A. Gordon Nicole D. Dretar Ted J. Ebersole Jyote C. Hyer Laura A. Vogel Michael J. Mancuso Bryan S. Wade Aaron L. Schwartz Michael G. Penn\* Shannon A. Carroll\* Wesley W. Jones\* Matthew E. Kelley\* Nicole R. Kramer\*

Registered Patent Agents-Karen R. Markowicz Nancy J. Leith Matthew J. Dowd Katrina Yujian Pei Quach Bryan L. Skelton Robert A. Schwartzman Teresa A. Colella Jeffrey S. Lundgren Victoria S. Rutherford Michelle K. Holoubek Simon J. Elliott Julie A. Heider Mita Mukherjee Scott M. Woodhouse Christopher J. Walsh Liliana Di Nola-Baron Peter A. Socarras Jeffrey Mills

Of Counsel Kenneth C. Bass III Evan R. Smith Marvin C. Guthrie

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WRITER'S DIRECT NUMBER: (202) 772-8645 INTERNET ADDRESS: JASONE@SKGF.COM

Art Unit 2823

Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450

Re:

U.S. Utility Patent Application

Application No. 10/750,834; Filed: January 5, 2004

For: High Density Metal Capacitor Using Via Etch Stopping Layer as Field

**Dielectric in Dual-Damascence Interconnect Process** 

Inventor:

Liming Tsau

Our Ref:

1875.0230001

Sir:

Transmitted herewith for appropriate action are the following documents:

- 1. Credit Card Payment Form (PTO-2038);
- 2. Amendment And Reply Under 37 C.F.R. 1.111;
- 3. Terminal Disclaimer To Obviate A Double Patenting Rejection Over a Prior Patent; and
- 4. One (1) Return Postcard.

It is respectfully requested that the attached postcard be stamped with the date of filing of these documents, and that it be returned to our courier. In the event that extensions of time are necessary to prevent abandonment of this patent application, then such extensions of time are hereby petitioned.

The U.S. Patent and Trademark Office is hereby authorized to charge any fee deficiency, or credit any overpayment, to our Deposit Account No. 19-0036.

Respectfully submitted,

STERNE, KESSLER, GOLDSTEÍN & FOX P.L.L.C.

Jason D. Eisenberg
Attorney for Applicant

Registration No. 43,44/

\$\$\text{PDF}/\text{Kexsler, Goldstein & Fox PLLC. : 1100 New York Avenue, NW : Washington, DC 20005 : 202.371.2600 f 202.371.2540s3; 1\text{15000cc}, skgf.com

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